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### (54) RESIN MOLDED THERMISTOR SENSOR

(57) Abstract:

**PURPOSE:** To obtain a resin molded thermistor sensor excellent in moisture resistance and heat shock resistance by injecting a specified urethane resin, as a mold resin, into the protective case for thermistor element.

**CONSTITUTION:** A thermistor element 1 connected with an insulated wire 4 is inserted into a protective case 5 injected with a liquid resin (mold resin) 6 or the liquid resin is injected after the thermistor element 1 is inserted into the protective case 5. Subsequently, the liquid resin 6 is cured to produce a resin molded thermistor. A two-liquid curing polybutadiene based urethane resin is employed as the mold resin. Cross-linked polyethylene or polyvinyl chloride is employed as the insulation coating 3 for the wire 4 and an epoxy resin or a moisture curing urethane resin is applied, as a plier, onto the surface of the insulation coating 3. This structure prevents interfacial delamination due to stress caused by differential thermal expansion thus ensuring high reliability for a long term.

